

PART No.	CODE No.	POS.	B	C	D
BM23PF0.8-10DP-0.35V(51)	-	10	3.49	1.40	2.70
BM23PF0.8-14DP-0.35V(51)	-	14	4.19	2.10	3.40
BM23PF0.8-20DP-0.35V(51)	-	20	5.24	3.15	4.45
BM23PF0.8-24DP-0.35V(51)	-	24	5.94	3.85	5.15
BM23PF0.8-30DP-0.35V(51)	-	30	6.99	4.90	6.20
BM23PF0.8-40DP-0.35V(51)	-	40	8.74	6.65	7.95
BM23PF0.8-42DP-0.35V(51)	-	42	9.09	7.00	8.30
BM23PF0.8-44DP-0.35V(51)	-	44	9.44	7.35	8.65
BM23PF0.8-46DP-0.35V(51)	-	46	9.79	7.70	9.00
BM23PF0.8-50DP-0.35V(51)	-	50	10.49	8.40	9.70
BM23PF0.8-54DP-0.35V(51)	-	54	11.19	9.10	10.40
BM23PF0.8-64DP-0.35V(51)	-	64	12.94	10.85	12.15

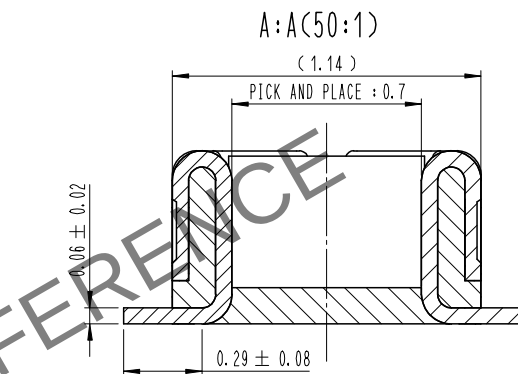
NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDER PLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)

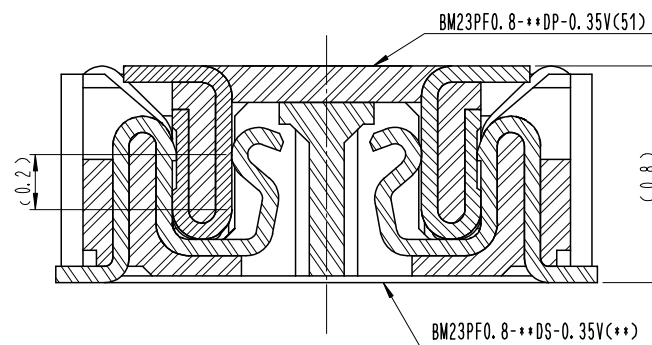
3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)

4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		
	2	RE-6-0742	LYJ	JHW	16	09	27		3	RE-6-1784	PSH	JHW	20	04	05
	3	RE-6-0806	MSH	JHW	17	01	05								
	1	RE-6-1137	KBJ	JHW	19	02	14								

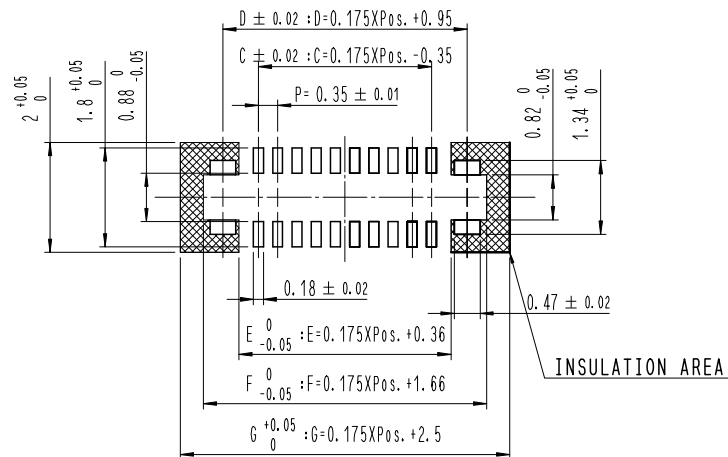


ENGAGEMENT FIGURE (50:1)



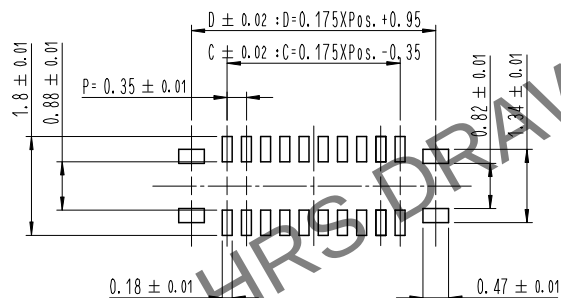
4	PS	CLEAR (EMBOSSED CARRIER TAPE)				7	PS	CLEAR(REINFORCEMENT COLLAR)			
3	COOPER ALLOY	3				6	PS	BLACK (PLASTIC REEL)			
2	COOPER ALLOY	2				5	POLYESTER	CLEAR (COVER TAPE)			
1	LCP	UL94 V-0, BLACK									
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS						
REMARKS							DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
							J. S. JANG	J. S. JANG	H. W. JO	H. W. JO	20.10.06
							20.10.06	20.10.06	20.10.06	20.10.06	
CODE NO. (OLD)							PART NO.				
							BM23PF0.8-***DP-0.35V(51)				
SCALE 10:1							CODE NO				
UNITS							CL 66***-***-51				
HRS HIROSE KOREA CO., LTD.							1/3				

7 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS

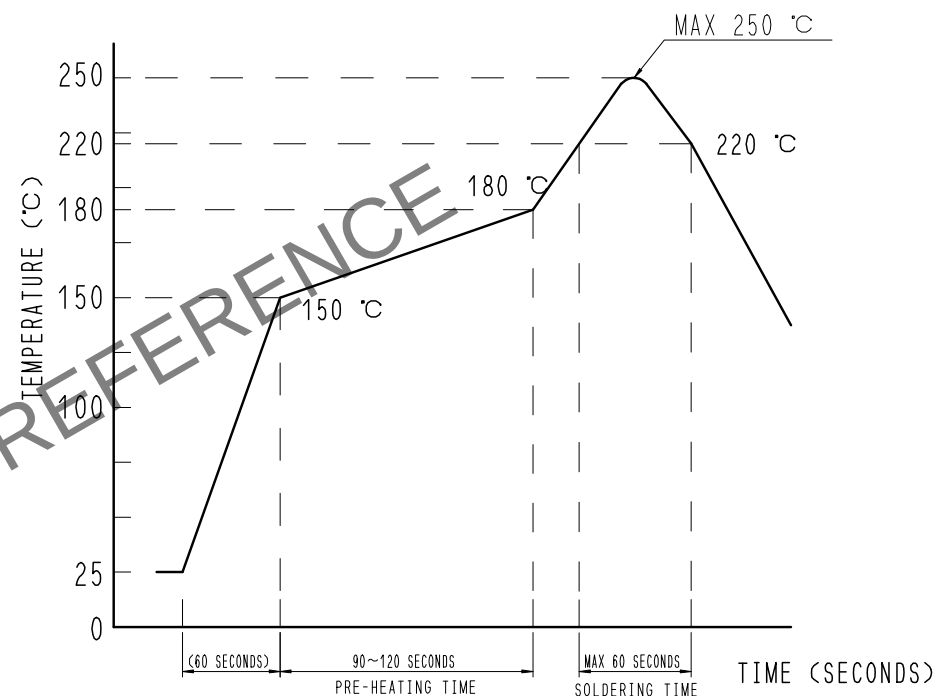
METAL MASK THICKNESS : 100 μ m



2/3/4

POS.	C	D	E	F	G
10	1.40	2.70	2.11	3.41	4.25
14	2.10	3.40	2.81	4.11	4.95
20	3.15	4.45	3.86	5.16	6.00
24	3.85	5.15	4.56	5.86	6.70
30	4.90	6.20	5.61	6.91	7.75
40	6.65	7.95	7.36	8.66	9.50
42	7.00	8.30	7.71	9.01	9.85
44	7.35	8.65	8.06	9.36	10.20
46	7.70	9.00	8.41	9.71	10.55
50	8.40	9.70	9.11	10.41	11.25
54	9.10	10.40	9.81	11.11	11.95
64	10.85	12.15	11.56	12.86	13.70

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N₂ REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C: 60 SEC MAX.

(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C

PRE-HEAT TEMPERATURE(MAX): 180°C

PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-**DP-0.35V(51)
SCALE	10:1	CODE NO	CL 66*-*****-51
UNITS	mm		

